Gas Discharge Tubes Datasheet





Web Resources



Download ECAD models, order samples, and find technical recources at <u>www.littelfuse.com</u>

Agency Approvals

| Agency | Agency File Number |
|-----------|--------------------|
| 91 | E128662 |

2 Electrode GDT Graphical Symbol



Description

Littelfuse SJ series GDT offers high surge ratings in a miniature package. It's designed for surface mounting on PCB with small size 4.5x3.2x3.2mm. Low insertion loss is perfectly suited to broadband equipment applications. SJ series has very low capacitances and shows slight signal losses up to high frequencies in application of high frequency data lines.

Features & Benefits

- RoHS compliant and Lead-free
- GHz working frequency
- Excellent stability on multiple pulse duty cycle
- Excellent response to fast rising transients.
- Ultra Low Insertion Loss
- 3-5KA surge capability tested with 8/20µS pulse

Applications

- Communication equipment
- CATV equipment
- Test equipment
- Data lines
- Power supplies
- Telecom SLIC protection

- Ultra small devices (EIA 1812)
- Non-Radioactive
- Low capacitance (<0.5pF)
- Voltage Ranges 90V to 1000V
- UL Recongized
- Conform to ITU-T Rec. K. 12; IEC 61643-311
- Square Outline
- Broadband equipment
- ADSL equipment, including ADSL2+
- XDSL equipment
- Satellite and CATV equipment
- General telecom equipment

Electrical Characteristics

| | Device Specifications (at 25°C) | | | | | | Life Ratings | | | | | | | |
|----------------|------------------------------------|------|-------------------------------|--|----------------|------------------------|---|-----------------------------------|--|--|---|-------------|--|------|
| Part Number | DC Breakdown in Volts (@100V/s) | | Breakdown Br in Volts In V | Impulse Breakdown In Volts (@1 KV/µsec) | (@1 Resistance | Capacitance (@1MHz) | Arc Voltage (on state Voltage) @1Amp Min | Surge Life (@10A 10/1000µs) | Nominal Impulse Discharge Current | npulse Discharge scharge Current urrent (10x1sec | Max Impulse Discharge Current (2 Application | | | |
| | Min. | Тур. | Max. | (0.10017 #07 | 100, 1000, | Min. | Max. | Тур. | | (8/20µs) | @50Hz) | @ 10/350µs) | | |
| SI90 | 72 | 90 | 108 | 500 | 600 | 109Ω at 50VDC | 50VDC | 8V | 300 shots 3 | 10 shots (@5kA), 300 shots (@100A) | 5A | 500A | | |
| SJ150 | 120 | 150 | 180 | 500 | 600 | 109Ω at | | 9V | | | | | | |
| SJ230 | 184 | 230 | 276 | 600 | 700 | 100VDC | | 10V | | | | | | |
| SJ600 | 480 | 600 | 720 | 1000 | 1100 | 109Ω at 100VDC | | | | | | | | 0007 |
| SJ800 | 640 | 800 | 960 | 1200 | 1300 | | | 0.5pF | 20V | 100 shots | 15 shots (@3kA) | ЗA | | |
| SJ1000 | 800 | 1000 | 1200 | 1400 | 1500 | | | TOOVDC | | | | | | |

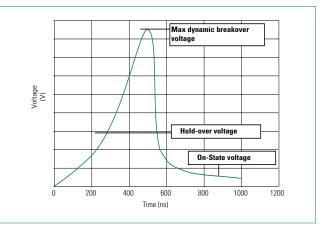
Product Characteristics

| Materials | Device Tin Plated 17.5±12.5 Microns Construction Ceramic Insulator. | | |
|--|--|--|--|
| Storage and Operational Temperature | -40 to +125 °C | | |

Typical Insertion Loss

| @ 1.0 GHz = 0.01 dB |
|---------------------|
| @ 1.4GHz = 0.1 dB |
| @ 1.8 GHz = 0.53 dB |
| @ 2.1 GHz = 0.81 dB |
| @ 2.45 GHz= 1 dB |
| @ 2.8 GHz = 1.2 dB |
| @ 3.1 GHz = 1.5 dB |
| @ 3.5 GHz = 2.1 dB |

Voltage vs. Time Characteristic



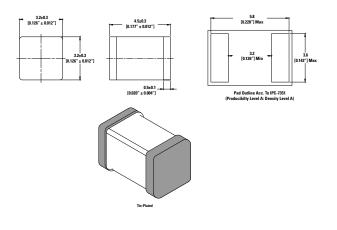
Critical Zone T_L to T_P

Ramp-down

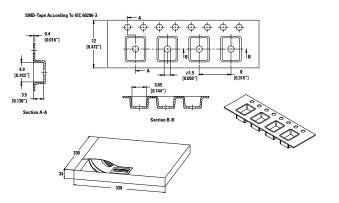
| | Soldering Para | meters - Reflow | Soldering (Surface Mount Devices) | | |
|--|--|-------------------------|-----------------------------------|--------|--|
| Reflow Condition | | Pb – Free assembly | | | |
| | - Temperature Min (T _{s(min)}) | 150°C | _ | tp ₄— | |
| Pre Heat | - Temperature Max (T _{s(max)}) | 200°C | Т _Р | | |
| | -Time (Min to Max) (t _s) | 60 – 180 secs | | | |
| Average ramp up rate (Liquidus Temp (T_L) to peak | | 3°C/second max | | | |
| T _{s(max)} to T _L - Ramp-up Rate | | 5°C/second max | | | |
| - Temperature (T _L) (Liquidus) | | 217°C | Preheat | | |
| Reflow | - Temperature (t _L) | 60 – 150 seconds | T _{S(min)} | | |
| Peak Temperature (T _p) | | 260 ^{+0/-5} °C | | | |
| Time within 5°C of actual peak Temperature (t _p) | | 10 – 30 seconds | 25 | | |
| Ramp-down Rate | | 6°C/second max | time to peak temperature | Time • | |
| Time 25°C to peak Temperature (T _P) | | 8 minutes Max. | (t 25°C to peak) | 11110 | |
| Do not exceed | | 260°C | | | |

Soldering Parameters - Reflow Soldering (Surface Mount Devices)

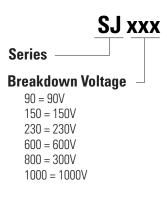
Device Dimensions



Tape and Reel Dimensions (IEC 60286-3, dimension in mm)



Part Numbering System and Ordering Information



Packaging

| Part Num | ber and Device Type | Quantity and Packaging Description | | |
|----------|---------------------|------------------------------------|--|--|
| SJxxx | Surface mount | 2200pcs/reel in tape and reel | | |

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